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A review of porous lightweight composite materials for electromagnetic interference shielding

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Contents

Abstract 1
1 Introduction 2
2 EMI shielding mechanisms and characterization methods 3
2.1 Shielding mechanism 3
2.2 Characterization 4
3 Porous EMI shielding materials 5
3.1 Syntactic foams 5
3.1.1 Conductive hollow particles 5
3.2 Syntactic foams with conductive filler 7
3.3 Foamed materials 8
3.3.1 Polymer based foam composites 8
3.3.2 Metal reinforced carbon foams 9
3.4 Effect of filler morphology and filler-matrix interaction 9
4 Conclusions 10
5 Acknowledgments 10
References 10
Figure captions 18
Figures 19

Abstract

Lightweight porous materials for electromagnetic interference (EMI) shielding applications are reviewed. EMI shielding refers to the capability of a material to protect from electromagnetic fields (EMFs) generated by electronic devices. Traditionally conducting metals are used in EMI shielding applications, which are slowly being replaced by conducting polymer based shields. This review is narrowly focused on understanding the approaches related to porous high EMI shielding composite materials that have very low density values. While conducting fillers can

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